

**AMENDMENTS TO THE CLAIMS:**

The following listing of claims replaces all prior listings, and all prior versions, of claims in the application.

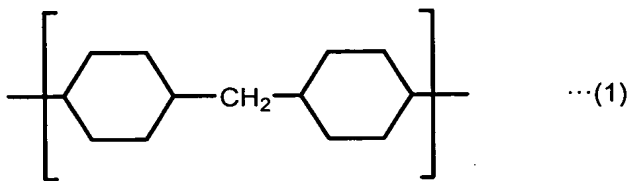
**LISTING OF CLAIMS:**

1. (Original) A prepreg obtained by impregnating a resin composition comprising a resin with an imide structure and a thermosetting resin into a fiber base material with a thickness of 5-50  $\mu\text{m}$ .

2. (Original) A prepreg according to claim 1, wherein said resin with an imide structure has a siloxane structure.

3. (Currently amended) A prepreg according to claim 1 ~~or 2~~, wherein said resin with an imide structure has a structure represented by the following general formula (1):

[Chemical Formula 1]

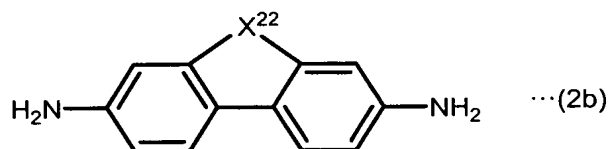
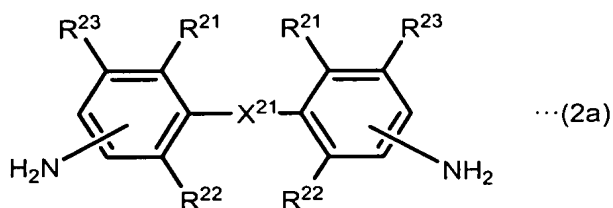


4. (Currently amended) A prepreg according to claim 1 ~~any one of claims 1 to 3~~, wherein said resin with an imide structure is a polyamideimide resin.

5. (Currently amended) A prepreg according to claim 1 ~~any one of claims 1 to 4~~, wherein said resin with an imide structure is a polyamideimide resin obtained

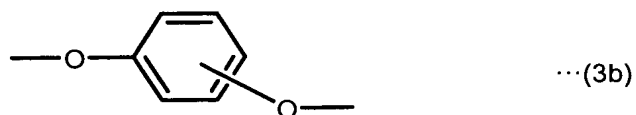
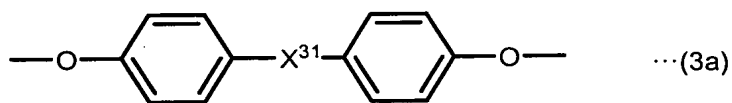
by reacting a diisocyanate compound with a mixture containing a diimidedicarboxylic acid obtained by reacting a mixture containing a siloxanediamine and a diamine represented by the following general formula (2a) or (2b) with trimellitic anhydride:-

[Chemical Formula 2]



[wherein  $X^{21}$  represents a C1-3 aliphatic hydrocarbon group, C1-3 halogenated aliphatic hydrocarbon group, sulfonyl group, ether group or carbonyl group, a single bond, a divalent group represented by the following general formula (3a) or a divalent group represented by the following general formula (3b),  $X^{22}$  represents a C1-3 aliphatic hydrocarbon group, C1-3 halogenated aliphatic hydrocarbon group, sulfonyl group, ether group or carbonyl group, and  $R^{21}$ ,  $R^{22}$  and  $R^{23}$  each independently or identically represent hydrogen, hydroxyl, methoxy, methyl or halogenated methyl:-

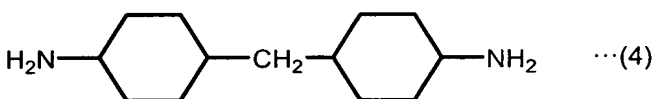
[Chemical Formula 3]



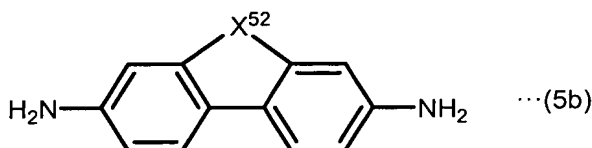
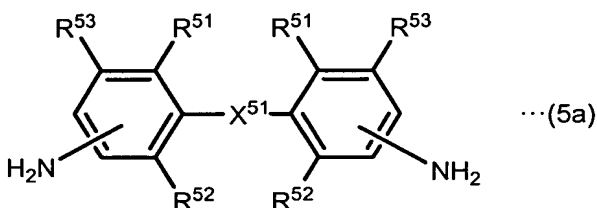
(wherein  $X^{31}$  represents a C1-3 aliphatic hydrocarbon group, C1-3 halogenated aliphatic hydrocarbon group, sulfonyl group, ether group or carbonyl group, or a single bond-)).

6. (Currently amended) A prepreg according to claim 1 ~~any one of claims 1 to 4~~, wherein said resin with an imide structure is a polyamideimide resin obtained by reacting a diisocyanate compound with a mixture containing a diimidedicarboxylic acid obtained by reacting a mixture containing a diamine represented by the following general formula (4), a siloxanediamine and a diamine represented by the following general formula (5a) or (5b), with trimellitic anhydride;

[Chemical Formula 4]



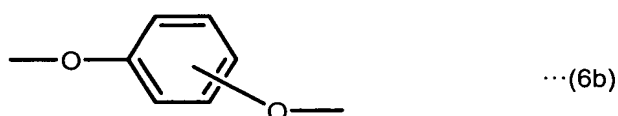
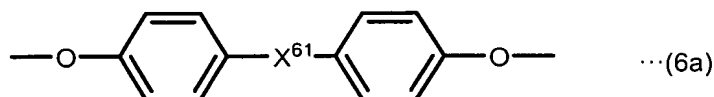
[Chemical Formula 5]



[wherein  $X^{51}$  represents a C1-3 aliphatic hydrocarbon group, C1-3 halogenated aliphatic hydrocarbon group, sulfonyl group, ether group or carbonyl group, a single bond, a divalent group represented by the following general formula (6a) or a divalent group represented by the following general formula (6b),  $X^{52}$  represents a

C1-3 aliphatic hydrocarbon group, C1-3 halogenated aliphatic hydrocarbon group, sulfonyl group, ether group or carbonyl group, and  $R^{51}$ ,  $R^{52}$  and  $R^{53}$  each independently or identically represent hydrogen, hydroxyl, methoxy, methyl or halogenated methyl:-

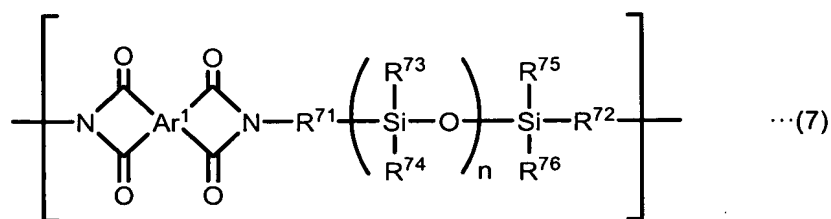
[Chemical Formula 6]



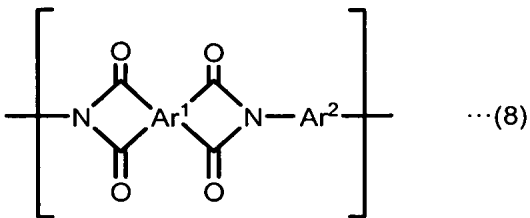
(wherein  $X^{61}$  represents a C1-3 aliphatic hydrocarbon group, C1-3 halogenated aliphatic hydrocarbon group, sulfonyl group, ether group or carbonyl group, or a single bond:-)].

7. (Currently amended) A prepreg according to claim 1 or 2, wherein said resin with an imide structure is a polyimide resin having the structure represented by the following general formula (7) or a polyimide resin having the structure represented by the following general formula (7) and the structure represented by the following general formula (8):-

[Chemical Formula 7]



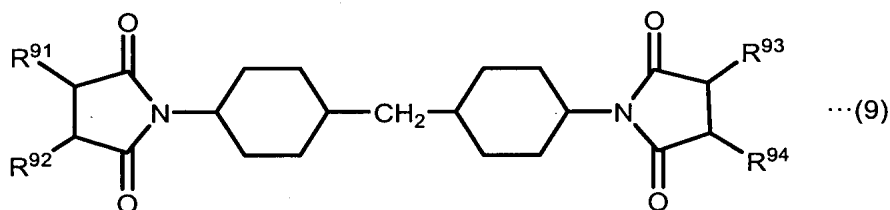
[Chemical Formula 8]



[wherein Ar<sup>1</sup> represents a tetravalent aromatic group, Ar<sup>2</sup> represents a divalent aromatic group, R<sup>71</sup> and R<sup>72</sup> each independently or identically represent a divalent hydrocarbon group, R<sup>73</sup>, R<sup>74</sup>, R<sup>75</sup> and R<sup>76</sup> each independently or identically represent a C1-6 hydrocarbon group, and n represents an integer of 1-50].

8. (Currently amended) A prepreg according to claim 1 ~~any one of claims 1 to 4~~, wherein said resin with an imide structure is a polyamideimide resin having the structure represented by the following general formula (9):

[Chemical Formula 9]



[wherein R<sup>91</sup>, R<sup>92</sup>, R<sup>93</sup> and R<sup>94</sup> each represent a carbon atom from a portion of the cyclic or linear structure composing the polyamideimide resin].

9. (Currently amended) A prepreg according to claim 1 ~~any one of claims 1 to 8~~, wherein said thermosetting resin is an epoxy resin.

10. (Currently amended) A prepreg according to claim 1~~any one of claims 1 to 9~~, wherein said thermosetting resin is an epoxy resin with two or more glycidyl groups.

11. (Currently amended) A prepreg according to claim 1~~any one of claims 1 to 10~~, wherein said resin composition further contains a phosphorus-containing compound, and said resin composition contains said thermosetting resin at 1-140 parts by weight with respect to 100 parts by weight of said resin with an imide structure, and phosphorus at 0.1-5 wt% of the total weight of the resin solid portion.

12. (Currently amended) A prepreg according to claim 1~~any one of claims 1 to 11~~, wherein said resin composition further contains a hindered phenol-based or organic sulfur compound-based antioxidant.

13. (Original) A prepreg according to claim 12, wherein said antioxidant is one or more types of antioxidant selected from the group consisting of butylated hydroxyanisole, 2,6-di-t-butyl-4-ethylphenol, 2,2'-methylene-bis(4-methyl-6-t-butylphenol), 4,4'-thiobis-(3-methyl-6-t-butylphenol), 4,4'-butylidenebis(3-methyl-6-t-butylphenol), 1,1,3-tris(2-methyl-4-hydroxy-5-t-butylphenyl)butane, 1,3,5-trimethyl-2,4,6-tris(3,5-di-t-butyl-4-hydroxybenzyl)benzene, tetrakis-[methylene-3-(3',5'-di-t-butyl-4'-hydroxyphenyl)propionate)methane, dilauryl thiodipropionate and distearyl thiodipropionate.

14. (Currently amended) A prepreg according to claim 1~~any one of claims 1 to 13~~, which has a combustion distance of no greater than 100 mm in a UL-94 VTM test, when cured to form a base material.

15. (Currently amended) A metal foil-clad laminate obtained by stacking a prescribed number of preregs according to claim 1~~any one of claims 1 to 14~~, situating a metal foil on either or both sides thereof and subjecting the stack to heat and pressure.

16. (Original) A printed circuit board obtained by forming a circuit on the metal foil of a metal foil-clad laminate according to claim 15.